INVENTORS NAME: Kie Y. Ahn et al. DOCKET NO.: 1303.016US1

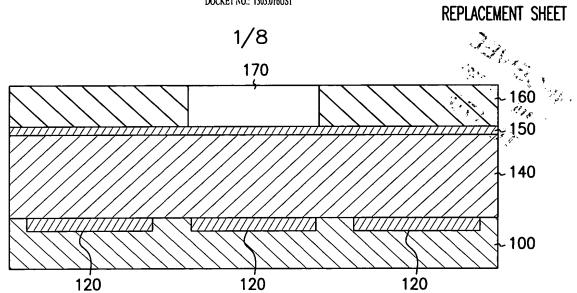


FIG. 1A (Prior Art)

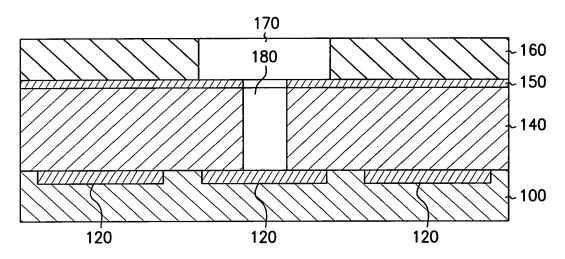


FIG. 1B (Prior Art)

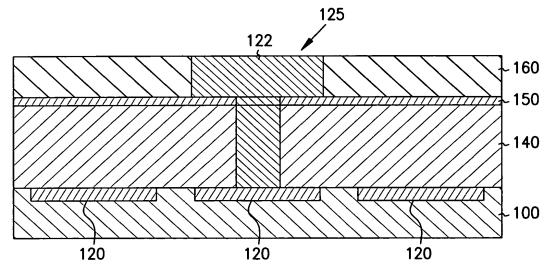


FIG. 1C (Prior Art)



## TILDER COPPER ELECTROLESS DEPOSITION TECHNOLOGY FOR ULSI METALIZATION INVENTORS NAME: Kie Y. Ahn et al.

DOCKET NO.: 1303.016US1

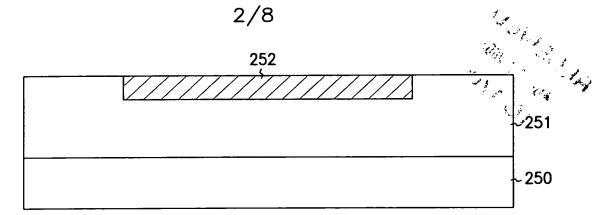


FIG. 2A

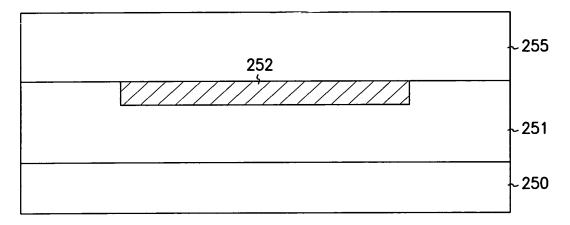


FIG. 2B

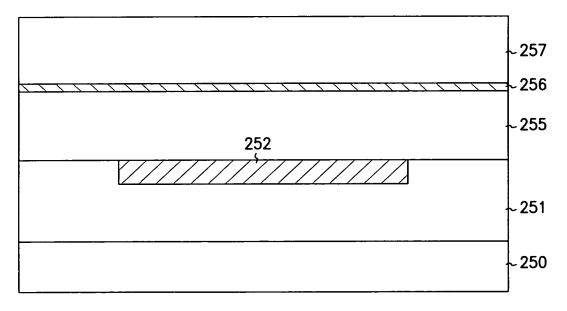


FIG. 2C



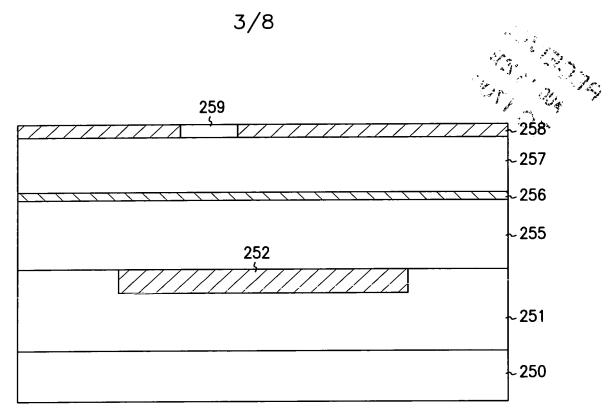


FIG. 2D

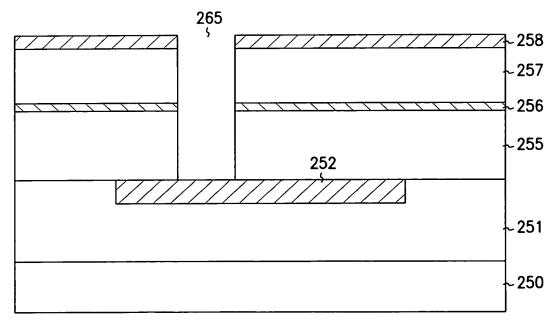


FIG. 2E



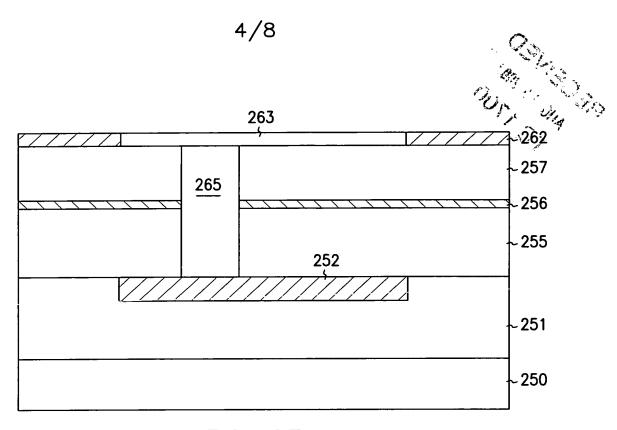


FIG. 2F

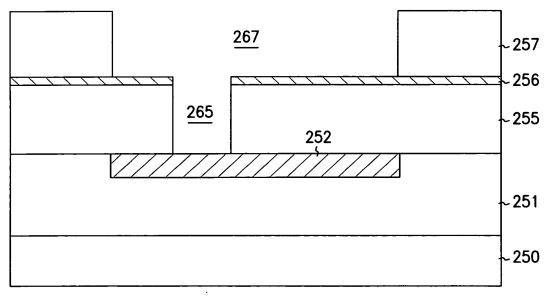


FIG. 2G



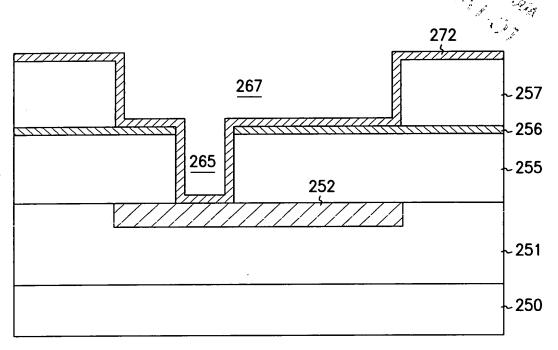


FIG. 2H

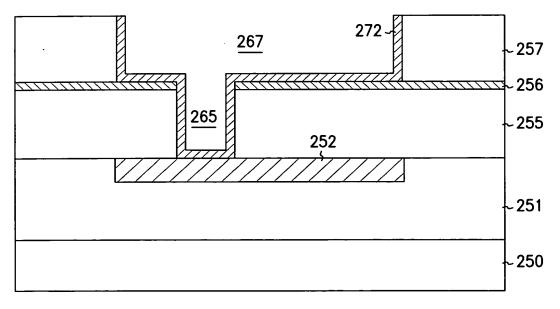


FIG. 21



DOCKET NO.: 1303.016US1

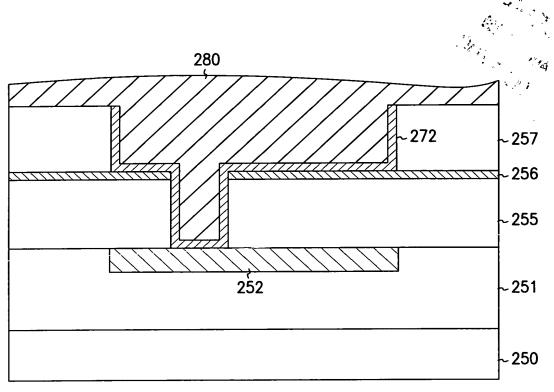


FIG. 2J

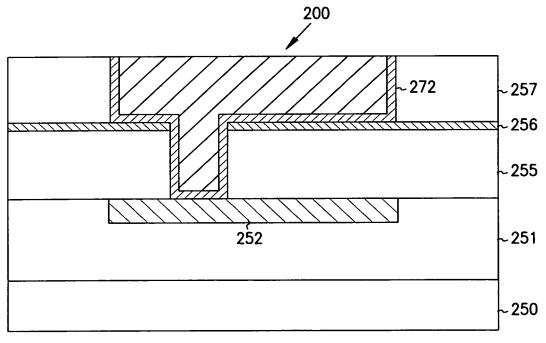


FIG. 2K





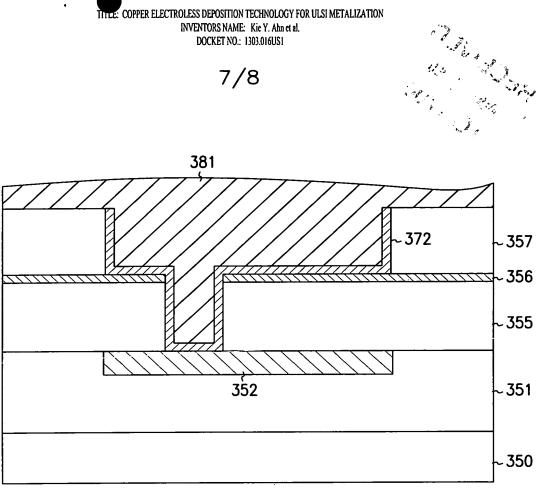


FIG. 3A

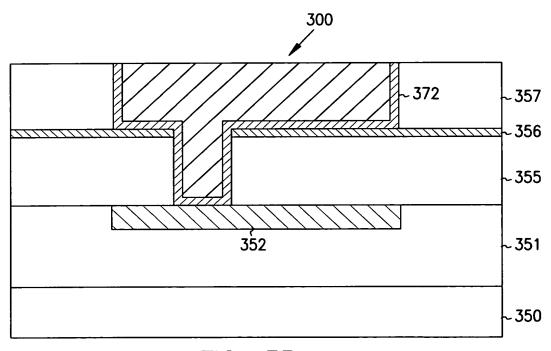


FIG. 3B



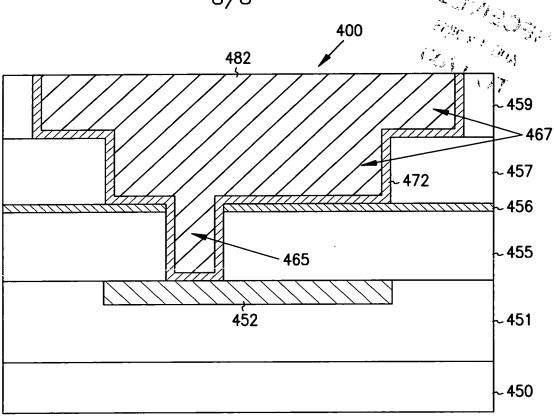


FIG. 4

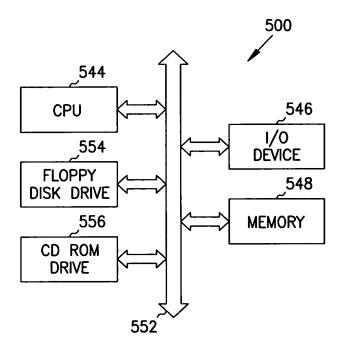


FIG. 5